Applications

- Coverage enhancement repeaters
- Femtocells
- Test Mobiles

Product Features

- Small form factor of 3.8 X 3.8 mm
- Max height of 1.2 mm
- Max Uplink/Downlink peak power of 38dBm
- Halogen and Lead free construction





3-pin 3.8x3.8mm leadless LGA package

Functional Block Diagram



General Description

TQM969001 is a duplexer designed for US PCS base station/repeater applications. It exhibits excellent power handling, pass band flatness, rejection, and Uplink/Downlink isolation.

The TQM969001 increases the sensitivity and dynamic range of receivers by providing more than 50 dB attenuation of the Uplink signal at the receiver input and more than 50 dB rejection of Uplink-generated noise in the receiver band.

Typical insertion loss at the Uplink channel is only 1.32 dB and the typical insertion loss in the Downlink channel is 1.52 dB, which improves the receiver sensitivity.

Pin Configuration

Pin #	Symbol
UpLink	1
DownLink	2
ANT	3

Ordering Information

Part No.	Description
TQM969001	PCS Duplexer
TQM969001EVB	PCS Duplexer evaluation board





Electrical Specifications

Test conditions unless otherwise not	red: +25°C	Min	Turrical	Max	l Inite
Antenna - Downlink	Conditions		Typical	wax	Units
Frequency (f _o)		1930.5		1989.5	MHz
Operating temperature		-40	+25	+85	С
Insertion loss	1930.5 – 1989.5 MHz		1.52	3.0	dB
Ripple (p-p)			0.84	1.25	dB
VSWR, 50 Ω	In/out		2.1:1	2.7:1	
Absolute attenuation	824 – 849 MHz	35	37		dB
Absolute attenuation	1850 – 1910 MHz	50	53		dB
Absolute attenuation	2400 – 2484 MHz	42	45		dB
Absolute attenuation	3860 – 3980 MHz	50	53		dB
Antenna – Uplink					
Frequency (f _o)		1850.5		1909.5	MHz
Operating temperature		-40	+25	+85	С
Insertion loss	1850.5 – 1909.5 MHz		1.32	2.8	dB
Ripple (p-p)			0.65	1.45	dB
VSWR, 50 Ω	In/out		1.8:1	2.1:1	
Absolute attenuation	869 – 894 MHz	38	41		dB
Absolute attenuation	1574.42 – 1576.42 MHz	40	43		dB
Absolute attenuation	1930 – 1990 MHz	44	50		dB
Absolute attenuation	3690 – 3830 MHz	27	30		dB
Absolute attenuation	5540 – 5740 MHz	15	17		dB
Absolute attenuation	7390 – 7650 MHz	12	24		dB
Uplink – Downlink					
Uplink – Downlink isolation	1850 – 1910 MHz	52	55		dB
	1930 – 1990 MHz	47	53		dB
	1910 - 1930 MHz	15	19		dB
Peak power			38		dBm
Average power	17,344 hours @ 55°C		29		dBm

Notes:

1. Network Analyzer is calibrated at -30 dBm power level for small signal measurements.

2. Triquint Test Board.



Device Characterization Data



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Device Characterization Data





Mechanical Information

The pad pattern shown has been developed and tested for optimized assembly at TriQuint Semiconductor. The PCB land pattern has been developed to accommodate lead and package tolerances. Since surface mount processes vary from company to company, careful process development is recommended.

Package Outline Drawing:









Bottom View



3-D View

Packaging Style: SIP LGA (system in package land grid array)



Recommend land-pad/approach pattern:







Recommended Land Pattern Solder Mask Opening



Recommended Land Pattern Stencil Aperture Style

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Tape and Reel Information

Tape and reel specifications for this part are also available on the TriQuint website in the "Application Notes" section.



MODULE – 3.8X3.8 CARRIER AND COVER TAPE DIMENSIONS

Part	Feature	Symbol	Size (in)	Size (mm)
Cavity	Length	A0	0.165	4.10
	Width	B0	0.165	4.10
	Depth	K0	0.055	1.80
	Pitch	P1	0.315	8.00
Distance Between Centerline	Cavity to Perforation	P2	0.079	2.00
	Length Direction			
	Cavity to Perforation	F	0.217	5.50
	Width Direction			
Cover Tape	Width	C	0.362	9.20
Carrier Tape	Width	W	0.472	12.00

TQM969001 PCS Duplexer



Product Compliance Information

ESD Information



ESD Rating:	Class 1C
Value:	Passes ≥ 1000 V min.
Test:	Human Body Model (HBM)
Standard:	JEDEC Standard JESD22-A114

Solderability

Compatible with the latest version of J-STD-020, Lead free solder, 260°

This part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)

MSL Rating

Level 3 at +260 °C convection reflow The part is rated Moisture Sensitivity Level 3 at 260°C per JEDEC standard IPC/JEDEC J-STD-020.

Recommended Soldering Temperature Profile



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